

High Speed SMD Switching Diode

FEATURES

- Fast switching device (t_{rr}<4.0ns)
- Surface mount device type
- Moisture sensitivity level 1
- Matte Tin (Sn) lead finish with Nickel (Ni) underplate
- Pb free and RoHS compliant
- Green compound (Halogen free) with suffix "G" on packing code and prefix "G" on date code











MECHANICAL DATA

- Case: Bend lead SOD-123 small outline plastic package

- Terminal: Matte tin plated, lead free, solderable per MIL-STD-202, Method 208 guaranteed

- High temperature soldering guaranteed : 260°C/10s

- Polarity: Indicated by cathode band

Weight: 10 ± 0.5 mgMarking Code: T4

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PARAMETER	SYMBOL	VALUE	UNIT
Power dissipation	P _D	350	mW
DC blocking voltage	V _R	100	V
Repetitive peak reverse voltage	V_{RRM}	100	V
Work peak reverse voltage	V_{RWM}	100	V
RMS reverse voltage	$V_{R(RMS)}$	70	V
Repetitive peak forward current	I _{FRM}	300	mA
Mean forward current	I _O	150	mA
Non-repetitive peak forward surge current @ t=1 ms @ t=10 ms	I _{FSM}	2.0 1.0	А
Thermal resistance (Junction to Ambient) (Note 1)	R _{θJA}	357	°C/W
Junction and storage temperature range	T _J , T _{STG}	-65 to + 150	°C

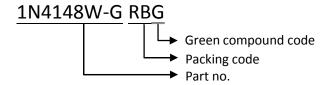
PARA	SYMBOL	MIN	MAX	UNIT	
Forward voltage	I _F =1.0mA		-	0.715	
	I _F =10mA	· · ·	-	0.855	7
	I _F =50mA	V _F	-	1.0	- V
	I _F =150mA		-	1.25	
	V _R =20V		-	25	nA
Reverse leakage current	V _R =75V		-	2.5	μA
	V _R =25V, Tj=150°C	I _R	-	30	μA
	V _R =75V, Tj=150°C		-	50	μA
nction capacitance V _R =0, f=1.0MHz		CJ	-	2.0	pF
Reverse recovery time (Note 2)		t _{rr}	-	4.0	ns

Notes: 1. Valid provided that terminals are kept at ambient temperature

Notes : 2. Reverse Recovery Test Conditions : I_F =10mA, I_R =10mA, R_L =100 Ω , I_{RR} =1mA

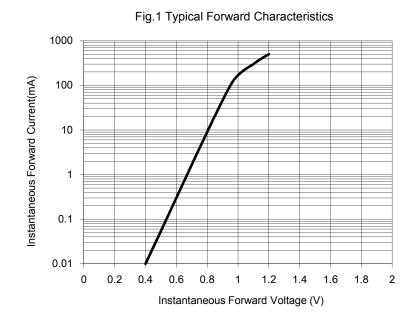


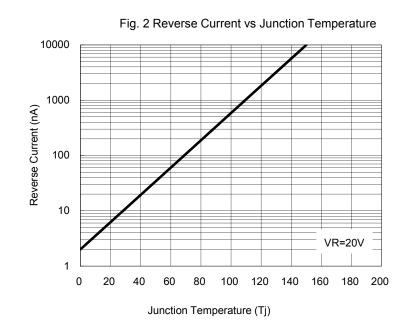
ORDER INFORMATION (EXAMPLE)



RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)

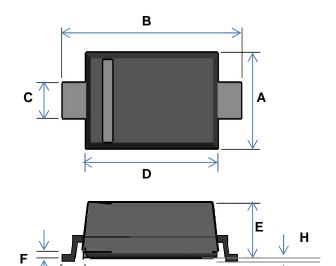






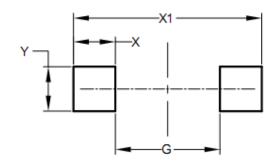
DIMENSIONS

SOD-123



DIM.	Unit (mm)		Unit (inch)		
DIIVI.	Min	Max	Min	Max	
Α	1.40	1.80	0.055	0.071	
В	3.55	3.85	0.140	0.152	
С	0.45	0.70	0.018	0.028	
D	2.55	2.85	0.100	0.112	
E	0.95	1.35	0.037	0.053	
F	0.05	0.15	0.002	0.006	
G	0.50 REF		0.02 REF		
Н	-	0.10	-	0.004	

SUGGESTED PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)
DIIVI.	Min	Min
G	2.25	0.089
Х	0.90	0.035
X1	4.05	0.159
Υ	0.95	0.037





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